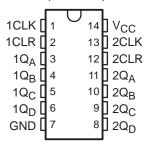
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 13 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Dual 4-Bit Binary Counters With Individual Clocks
- Direct Clear for Each 4-Bit Counter
- Can Significantly Improve System
 Densities by Reducing Counter Package
 Count by 50 Percent

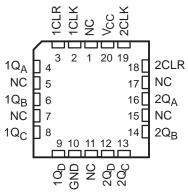
description/ordering information

The 'HC393 devices contain eight flip-flops and additional gating to implement two individual 4-bit counters in a single package. These devices comprise two independent 4-bit binary counters, each having a clear (CLR) and a clock (CLK) input. N-bit binary counters can be implemented with each package, providing the capability of divide by 256. The 'HC393 devices have parallel outputs from each counter stage so that any submultiple of the input count frequency is available for system timing signals.

SN54HC393 . . . J OR W PACKAGE SN74HC393 . . . D, DB, N, NS, OR PW PACKAGE (TOP VIEW)



SN54HC393 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC393N	SN74HC393N
		Tube of 50	SN74HC393D	
	SOIC - D	Reel of 2500	SN74HC393DR	HC393
		Reel of 250	SN74HC393DT	
-40°C to 85°C	SOP - NS	Reel of 2000	SN74HC393NSR	HC393
	SSOP - DB	Reel of 2000	SN74HC393DBR	HC393
		Tube of 90	SN74HC393PW	
	TSSOP - PW	Reel of 2000	SN74HC393PWR	HC393
		Reel of 250	SN74HC393PWT	
	CDIP – J	Tube of 25	SNJ54HC393J	SNJ54HC393J
−55°C to 125°C	CFP – W	Tube of 150	SNJ54HC393W	SNJ54HC393W
	LCCC – FK	Tube of 55	SNJ54HC393FK	SNJ54HC393FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



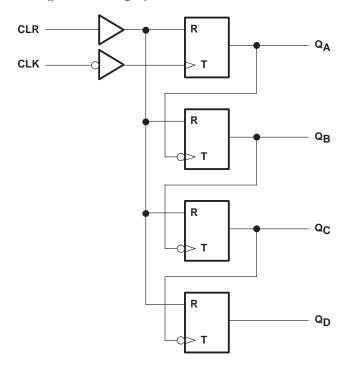
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FUNCTION TABLE COUNT SEQUENCE (each counter)

COUNT		OUTI	PUTS	
COUNT	Q_{D}	QC	Q_{B}	Q_{A}
0	L	L	L	L
1	L	L	L	Н
2	L	L	Н	L
3	L	L	Н	Н
4	L	Н	L	L
5	L	Н	L	н
6	L	Н	Н	L
7	L	Н	Н	Н
8	Н	L	L	L
9	Н	L	L	Н
10	Н	L	Н	L
11	Н	L	Н	Н
12	Н	Н	L	L
13	Н	Н	L	н
14	Н	Н	Н	L
15	Н	Н	Н	Н

logic diagram, each counter (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}		0.5	V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see	ee Note 1)		±20 mA
Output clamp current, IOK (VO < 0 or VO > VCO	C) (see Note 1)		±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})			
Continuous current through V _{CC} or GND			±50 mA
Package thermal impedance, θ_{JA} (see Note 2)	: D package		86°C/W
, ,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	DB package		96°C/W
	N package		80°C/W
	NS package		76°C/W
	PW package	′	113°C/W
Storage temperature range, T _{stg}		–65°C f	to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		SN54HC393		SN	174HC39	3	UNIT		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
VIH	VIH High-level input voltage	$V_{CC} = 4.5 \text{ V}$	3.15			3.15			V
		V _{CC} = 6 V	4.2			4.2			
		V _{CC} = 2 V			0.5			0.5	
VIL	Low-level input voltage	$V_{CC} = 4.5 \text{ V}$			1.35			1.35	V
		V _{CC} = 6 V			1.8			1.8	
VI	Input voltage		0		VCC	0		VCC	V
Vo	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V			1000			1000	
Δt/Δν†	Input transition rise/fall time	V _{CC} = 4.5 V			500			500	ns
		VCC = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at VCC or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[†] If this device is used in the threshold region (from V_{IL}max = 0.5 V to V_{IH}min = 1.5 V), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at t_t = 1000 ns and V_{CC} = 2 V does not damage the device; however, functionally, the CLK inputs are not ensured while in the shift, count, or toggle operating modes.

SCLS143D - DECEMBER 1982 - REVISED JULY 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO	ONDITIONS	Vaa	Т	A = 25°C	;	SN54H	C393	SN74H	C393	UNIT
PARAMETER	1251 CC	CNDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		
Voн	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1		0.1		0.1	
VOL	$V_I = V_{IH}$ or V_{IL}		6 V		0.001	0.1		0.1		0.1	V
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
Icc	$V_I = V_{CC}$ or 0,	I _O = 0	6 V			8		160		80	μΑ
Ci		·	2 V to 6 V		3	10		10		10	pF

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			V	T _A = 1	25°C	SN54H	IC393	SN74H	IC393	UNIT
			VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNII
			2 V		6		4.2		5	
fclock	Clock frequency		4.5 V		31		21		25	MHz
		6 V		36		25		28		
			2 V	80		120		100		
		CLK high or low	4.5 V	16		24		20		ns
١.	Pulse duration		6 V	14		20		18		
t _W	Fuise duration		2 V	80		120		100		115
		CLR high	4.5 V	16		24		20		
			6 V	14		20		18		
		·	2 V	25		25		25		
t _{SU} Setup time, CLR inactive			4.5 V	5		5		5		ns
			6 V	5		5		5		

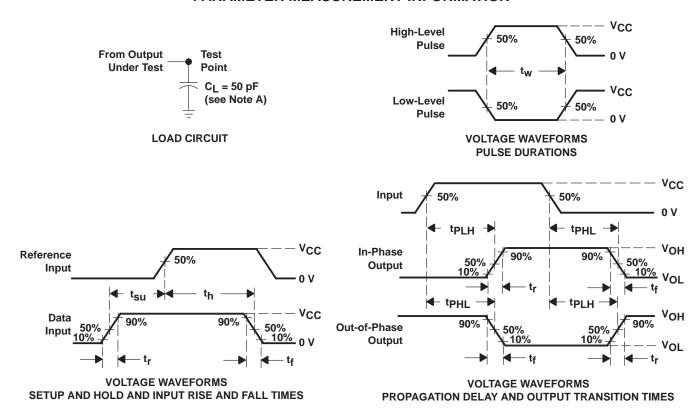
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	,,	T,	Δ = 25°C	;	SN54F	IC393	SN74H	IC393		
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
			2 V	6	10		4.2		5			
f _{max}	CLK	Q_A	4.5 V	31	50		21		25		MHz	
			6 V	36	60		25		28			
			2 V		50	120		180		150		
		Q_A	4.5 V		15	24		36		30		
			6 V		13	20		31		26		
			2 V		72	190		285		240		
	CLK		Q_{B}	4.5 V		22	38		57		47	
			6 V		18	32		48		40	ns	
^t pd			2 V		91	240		360		300	113	
		QC	4.5 V		28	48		72		60		
			6 V		22	41		61		51		
			2 V		100	290		430		360		
		Q_{D}	4.5 V		32	58		87		72		
			6 V		24	50		74		62		
			2 V		45	165		250		205		
t _{PHL}	CLR	Any	4.5 V		17	33		49		41	ns	
			6 V		14	28		42		35		
			2 V		28	75		110		95		
t _t		Any	4.5 V		8	15		22		19	ns	
			6 V		6	13		19		16		

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per counter	No load	40	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f = 6$ ns, $t_f = 6$ ns.
- C. For clock inputs, $f_{\mbox{\scriptsize max}}$ is measured when the input duty cycle is 50%.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms







30-May-2005

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finis	h MSL Peak Temp ⁽³⁾
84100012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
8410001CA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
8410001DA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/66309BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54HC393J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN74HC393D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC393DBR	ACTIVE	SSOP	DB	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC393DBRE4	ACTIVE	SSOP	DB	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC393DE4	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC393DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC393DRE4	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC393DT	ACTIVE	SOIC	D	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC393DTE4	ACTIVE	SOIC	D	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC393N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC393N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74HC393NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC393NSRE4	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74HC393PW	ACTIVE	TSSOP	PW	14	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC393PWE4	ACTIVE	TSSOP	PW	14	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC393PWR	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC393PWRE4	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC393PWT	ACTIVE	TSSOP	PW	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC393PWTE4	ACTIVE	TSSOP	PW	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SNJ54HC393FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54HC393J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54HC393W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.



PACKAGE OPTION ADDENDUM

30-May-2005

PREVIEW: Device has been announced but is not in production. Samples may or may not be available. **OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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